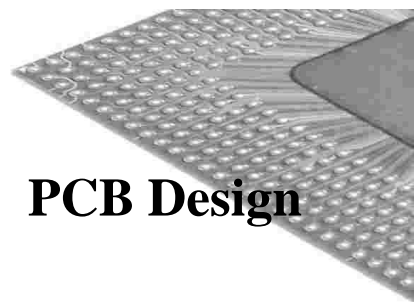


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PCB Design

<i>Project:</i>	4467 - Direction finding application
<i>Title:</i>	PCB Laminate Specification for PCB 400503

Revision History Control

Rev.	Rev. Date	Document Status	Responsible
1.0.0	2020-02-13	First version	KJP

Changes since Last Revision

Change #	Changes

References

Ref. No.	Doc. No.	Rev.	Title

1. PCB laminate parameters

PCB Supplier	<i>Suppliers choice</i>
Number of copper layers	<i>4 layers</i>
Laminate material	<i>FR4</i>
Total board thickness	<i>1.6mm</i>
PCB stackup	<i>See figure 1</i>
Copper thickness	<i>See figure 1</i>
Solder Mask Color	<i>Green</i>
Silkscreen Color	<i>White</i>
Surface finish	<i>ENIG Gold</i>
Compliance with environmental directives	<i>RoHS</i>

Table 1 PCB substrate details

The PCB layer stackup order (from top layer and down) shall be as follows with reference to the Gerber file extensions given below:

- Top layer: .GTL
- Mid-layer 1: .G1
- Mid-layer 2: .G2
- Bottom Layer: .GBL

LAYER	NAME OF LAYER	TYPE	THICKNESS mm	VIAS
1	EXTERNAL COPPER	12µm + GalvCu 35µm	0.047	
	PREPREG	7628-45 (0,18mm)	0.18	
2	INNER FOIL	35µm	0.035	
	INNERLAYER	High Tg 1,08mm 35µm/35µm	1.08	
3	INNER FOIL	35µm	0.035	
	PREPREG	7628-45 (0,18mm)	0.18	
4	EXTERNAL COPPER	12µm + GalvCu 35µm	0.047	
		THICKNESS (mm) ±10%	1.604	

Figure 1: 4 layer stackup